



Board Characteristics - 4 LAYER BOARD

- 0. All dimensions are given in inches unless specified otherwise.
- 1. Material FR4
- 2. Minimum trace width and clearance: 0.005"
- 4. 1 oz copper for all power layers and for Signal_1,2 (Top and Bottom)
- 5. Immersion Gold over copper, with min. Ni: 2.5-5 um; Au: 0.05-0.2 um.
Apply Solder Mask over bare copper.
- 6. Board Thickness: 0.063 +/- 0.008
- 8. Silkscreen on Component and Solder Sides.
- 9. 45 degree chamfer.
- 10. FHS tolerances: +/- 0.003
- 11. Interlayer spacing as specified
- 12. Trace Impedance: Zc=50 Ohm +/- 10%

BOARD'S DRILL SCHEDULE

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Tolerance	COMMENT
○	.014	711	YES	---	
⊞	.041	389	YES	---	
⊕	.057	4	YES	---	
⊞	.106	6	NO	---	
⊖	.15	1	NO	---	

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES .XX .XXX DO NOT SCALE DRAWING	CONTRACT NO.		UNIVERSITY OF CHICAGO ELECTRONICS DEVELOPMENT GROUP			
	APPROVALS	DATE	TITLE ADC Master Specification Drawing			
	DRAWN M. Bogdan	9/1/11	SIZE B	FSCM NO.	DWG. NO. 2755	REV. B
	CHECKED M. Bogdan	9/1/11	SHEET			
FINISH	ISSUED	SCALE 1/2				
SIMILAR TO	ACT. WT	CALC WT				